

# TO-B1608BC-HC

## Surface Mount Device LED

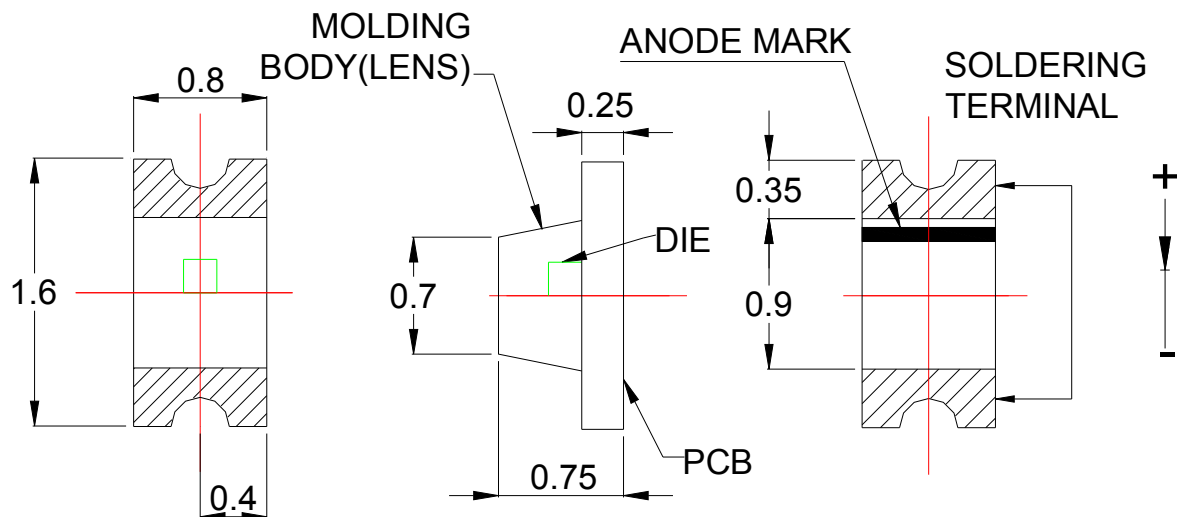


Part Number	Chip		Lens Color
	Material	Source Color	
TO-B1608BC-HC	AlGaInp	Red	Water Clear

### Features

- IC compatible.
- Compatible with automatic placement equipment.
- Compatible with infrared and vapor phase Reflow solder process.
- Top View TYPE.
- Package in 8mm tape on 7" diameter reel.
- Lead-Free Package (According to RoHS).

### Dimensions



Notes:

1. All dimensions are in millimeter.
2. Tolerance is  $\pm 0.1$ mm unless individual mark noted.

### Absolute Maximum Rating @ Ta=25°C

Parameter	Maximum Rating	Unit
Peak Forward Current (1/10 Duty Cycle, 0.1ms Pulse Width)	80	mA
Power Dissipation	75	mW
Continuous Forward Current	25	mA
Reverse Voltage	5	V
Operating Temperature Range	-55°C to +85°C	
Storage Temperature Range	-55°C to +105°C	
IR Reflow Soldering Profile For Lead Free Soldering	260°C	

### Electrical / Optical Characteristic @ Ta=25°C

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Condition
Luminous Intensity	Iv	10.5		30	mcd	I <sub>F</sub> =20mA
Viewing Angle	2θ1/2		130		deg	I <sub>F</sub> =20mA
Forward Voltage	V <sub>F</sub>		2.0		V	I <sub>F</sub> =20mA
Dominant Wavelength	λ <sub>d</sub>		644		nm	I <sub>F</sub> =20mA
Spectral Line Half-Width	Δλ		20		nm	I <sub>F</sub> =20mA
Reverse Current	I <sub>R</sub>			10	μA	V <sub>R</sub> =5V